

RoHS Compliant



| REV | MODIFICATION | DATE | DRAW |
|-----|------------------------|------------|----------|
| A5 | Release To ECN20130516 | 2013.05.31 | Michelle |
| B0 | Release To ECN20150607 | 2015.06.18 | Michelle |
| B1 | Release To ECN20160103 | 20160112 | Michelle |

Specification

- 1.Current Rating:2A AC/DC
- 2.Voltage Rating:250V AC/DC
- 3.Contact Resistance:20mΩ Max.
- 4.Insulation Resistance:1000MΩ Min.
- 5.Dielectric Withstanding Voltage:AC800V/Minute
- 6.Operating Temperature:-25°C~+85°C

Material:

- 1.Housing:High Temperature Thermoplastic UL94V-0
- 2.Contact Pin:Copper Alloy SQ. Pin 0.50mm

Finish:

- 1.Housing:See P/N Option
- 2.Contact Pin:See P/N Option

Part No.:AD05801 XX X X 5 2

No. Of Pin
04~40

Packing
5:Bag

Housing Material


- 4:Nylon66+Glass Fiber
- UL94V-0 Natural

Plating

- 1:Bright Tin Plated Over Nickel
- 2:Matte Tin Plated Over Nickel
- 3:Gold Plated Over Nickel


- △A5 A:Nylon66+Glass Fiber
UL94V-0 Black

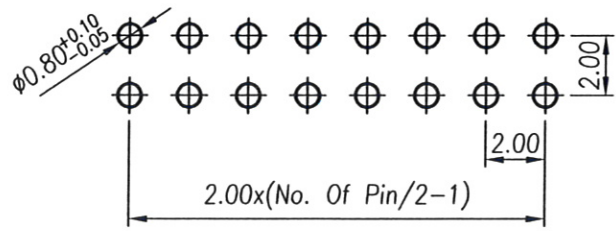
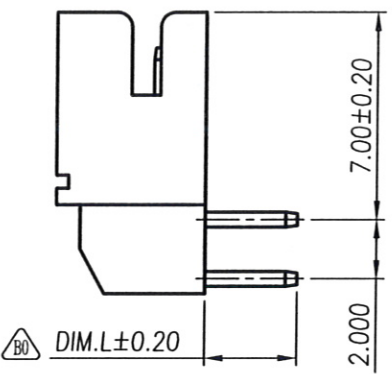
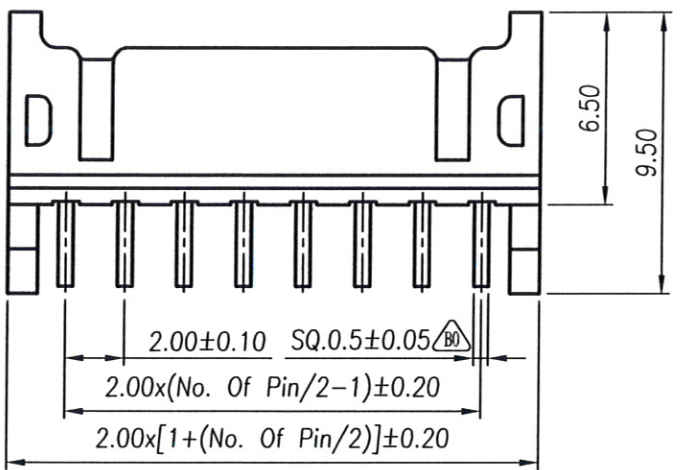
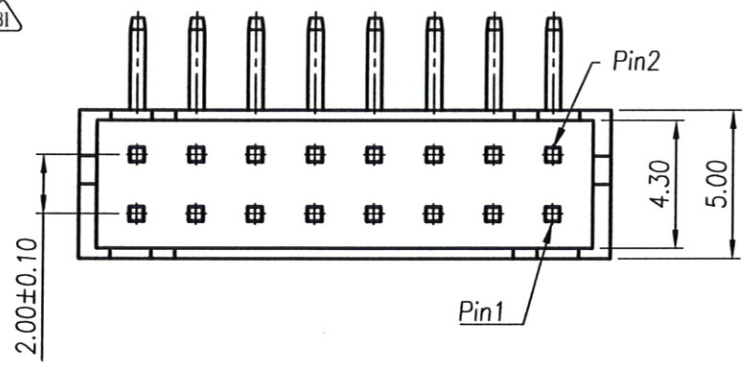
| P/N | DIM.L |
|---------------|-------|
| AD05801XXXX52 | 3.10 |
| AD05869XXXX52 | 2.50 |



金上達科技股份有限公司

GOLDENSUND TECHNOLOGY CO.,LTD

| | | | | |
|--------------------------------------|-----------|---|--|-------------------------|
| TOLERANCE UNLESS OTHERWISE SPECIFIED | | PROJ.  | TITLE: Wire To Board Wafer 2.00mm 90° DIP Dual Row | |
| .x± 0.35 | x.± 2' | APR. C.F. Liao 20160112 | PART NO. AD058XXXXX52 | DWG NO. AD058XXXXX52 |
| .xx± 0.25 | .x± 1' | CHK. Abel 20160112 | UNITS: mm | |
| .xxx± 0.15 | .xx± 0.5' | DRA. Michelle 20160112 | CUSTOMER DRAWING | |
| | | SIZE: A4 | SCALE: 4:1 | SHEET 1 / 1 |
| | | | REV: B1 | V |



△B0 RECOMMENDED P.C.B LAYOUT

